PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

EPAS ID: PAT3323491

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
CHIH CHENG HSIEH	04/20/2015
HSIU WEN HSU	04/20/2015

RECEIVING PARTY DATA

Name:	NIKO SEMICONDUCTOR CO., LTD.
Street Address:	12F., NO.368, GONGJIAN RD., XIZHI DIST.
City:	NEW TAIPEI CITY
State/Country:	TAIWAN
Postal Code:	221
Name:	SUPER GROUP SEMICONDUCTOR CO., LTD.
Street Address:	6F., NO.366, GONGJIAN RD., XIZHI DIST.
City:	NEW TAIPEI CITY
State/Country:	TAIWAN
Postal Code:	221

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14694256

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	103P001216US
NAME OF SUBMITTER:	ZHUO XU
SIGNATURE:	/ZHUO XU/

DATE SIGNED:	04/23/2015

Total Attachments: 3
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ASSIGNMENT DEED

Attorney docket No.________________

This Assignment agreement is applicable to an invention entitled (invention Title):

MANUFACTURING METHOD OF WAFER LEVEL CHIP SCALE PACKAGE STRUCTURE

The PATENT RIGHTS referred to in this agreement are:

(Check one)

☒ a Patent Application for this invention, executed by the ASSIGNOR(S) concurrently with this Assignment
☐ U.S. Patent Application Serial No. ________________, filed ________________
☐ U.S. Patent No. ________________, issued ________________

The PATENT RIGHTS assigned under this agreement are:

(Check One)

☒ U.S. Patent rights only

☐ worldwide Patent rights. In this case, the assignee shall have the right to claim the benefit of the filing date of any U.S. Patent Application identified above.

I/WE believe that I/WE am/are the original inventor(s) of a claimed invention in the application.

The above-identified Application was made or authorized by me/us.

I/WE hereby acknowledge that any will false statements made in this Assignment is punishable under 18 USC 1001 by fine or imprisonment of not more than five (5) years, or both.

The ASSIGNOR(S) referred to in this agreement is (or are):

(Full name of sole or first assignor) CHIH CHENG HSIEH (FAMILY NAME: HSIEH)

(Address) NO. 1, ALY. 16, LN. 50, LONGQING ST., ZHONGLI CITY, TAOYUAN COUNTY 320, TAIWAN, R.O.C.

(Full name of second joint assignor, if any) HSIU WEN HSU (FAMILY NAME: HSU)

(Address) NO. 15, ALLEY 7, LANE 197, SHANGREN ST., XINFENG SHIANG, HSINCHU COUNTY 304,
TAIWAN, R.O.C.

(Full name of third joint assignor, if any)________________

(Address)________________

(Full name of fourth joint assignor, if any)________________

(Address)________________

☐ Additional assignors are being named on separately numbered sheets attached hereto.

The sole or first ASSIGNEE(S) referred to in this agreement is (or are):

(Name of Assignee) NIKO SEMICONDUCTOR CO., LTD.

(Address) 12F., NO.368, GONGJIAN RD., XIZHI DIST., NEW TAIPEI CITY 221, TAIWAN, R.O.C.

The sole or first ASSIGNEE is: (Check One)

☐an individual
☐ a partnership
▨ a Corporation of TAIWAN, R.O.C. (State or Country)

The second ASSIGNEE(S) (if any) referred to in this agreement is (or are):
(Name of Assignee) SUPER GROUP SEMICONDUCTOR CO., LTD.
(Address of Assignee) 6F., NO.366, GONGJIAN RD., XIZHI DIST., NEW TAIPEI CITY 221, TAIWAN, R.O.C.

The second ASSIGNEE is: (Check One)

☐an individual
☐ a partnership
▨ a Corporation of TAIWAN, R.O.C. (State or Country)

The third ASSIGNEE(S) (if any) referred to in this agreement is (or are):
(Name of Assignee) ________________
(Address of Assignee)________________

☐ Additional assignees are being named on separately numbered sheets attached hereto.

The ASSIGNOR(S), in consideration of $1.00 paid by each ASSIGNEE, and other good and valuable consideration, receipt of which is acknowledged, have and do hereby assign the following to each ASSIGNEE; their successors and assigns:

the full and exclusive right to the invention;

an equal interest in and to the entire right, title and interest in and to the PATENT RIGHTS in the invention, all continuations, continuations-in-part, divisionals, re-issues, and re-examination patents and patent applications; and

the right to claim priority under 35 U.S.C. § 119, based on any earlier foreign applications for this invention.

As to all U.S. Patent Applications assigned under this Agreement, the ASSIGNOR(S) hereby authorize(s) and request(s) the Commissioner of Patents and Trademarks to issue all Letters Patent to the ASSIGNEE(S) as the ASSIGNEE(S) of an equal interest in the entire right, title and interest, for the sole use and enjoyment of said ASSIGNEE(S), their successors and assigns.

Further, the ASSIGNOR(S) agree(s) to communicate to said ASSIGNEE(S), or their representatives, any facts known to the ASSIGNOR(S) respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, substitute, renewal, reexamination and reissue applications, execute all necessary assignment papers to cause any and all Letters Patent to be issued to said ASSIGNEE(S), make all rightful oaths and generally do everything necessary or desirable to aid said ASSIGNEE(S), their successors and assigns, to obtain and enforced proper protection for said invention.

I hereby give our Attorney authorization to insert the Serial Number and filing date of the above-referenced Patent Application when known.

CHIH CHENG HSIEH (FAMILY NAME: HSIEH)
(Signature of sole or first assignor) APRIL 20, 2015 (Date)

Hsiu-wen Hsu HSIU WEN HSU (FAMILY NAME: HSU)
(Signature of second assignor, if any) APRIL 20, 2015 (Date)

(Signature of third assignor, if any) (Date)

(Signature of fourth assignor, if any) (Date)

(Signature of fifth assignor, if any) (Date)

(Signature of sixth assignor, if any) (Date)